

Title (en)

Method for the fabrication of a multi-layered patina and said multi-layered patina

Title (de)

Multischicht-Patina und Verfahren zum Herstellen einer multischicht-Patina

Title (fr)

Procédé de fabrication d'une patine ayant une structure multicouchee et patine avec cette structure multicouchee

Publication

**EP 1643006 A3 20060906 (EN)**

Application

**EP 05020621 A 20050921**

Priority

FI 20041256 A 20040929

Abstract (en)

[origin: EP1643006A2] The invention relates to a method for forming a patina surface on a substrate, which is preferably made of copper or copper alloy. According to the method, the patina surface is formed on top of the surface of the substrate material in at least two different layers of corrosive patination material, of which the colour and/or composition differ from each other. The invention also relates to the patina, which is formed as at least two layers.

IPC 8 full level

**C23C 22/76** (2006.01); **C23C 8/02** (2006.01); **C23C 8/10** (2006.01); **C23C 22/63** (2006.01); **C23C 28/04** (2006.01)

IPC 8 main group level

**C09D** (2006.01)

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**C23C 8/02** (2013.01); **C23C 8/10** (2013.01); **C23C 22/63** (2013.01); **C23C 22/76** (2013.01); **C23C 28/04** (2013.01)

Citation (search report)

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- [X] DATABASE COMPENDEX [online] ENGINEERING INFORMATION, INC., NEW YORK, NY, US; FRANEY J P ET AL: "STRUCTURE OF COPPER PATINA PRODUCED BY EXTENDED ATMOSPHERIC EXPOSURE", XP002389243, Database accession no. EIX87030047774
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